

48. Packaging Information

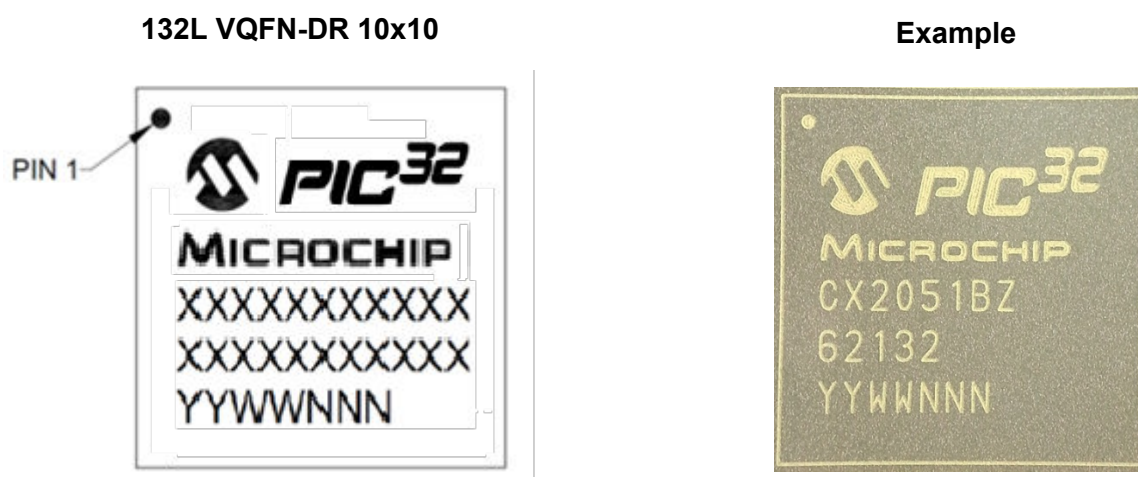
This chapter provides information on package markings, dimension and footprint of the PIC32CX-BZ6 and the PIC32WM-BZ6 family.

48.1. PIC32CX-BZ6 SoC Packaging Information

For the most current package drawings, see the Microchip Packaging Specification located at www.microchip.com/en-us/support/package-drawings.

48.1.1. PIC32CX-BZ6 SoC Package Marking

Figure 48-1. PIC32CX2501BZ62132 Package Marking



Legend:

XX...X: Customer-specific information
 Year code (last digit of calendar year)
 YY: Year code (last 2 digits of calendar year)
 WW: Week code (week of January 1 is week "01")
 NNN: Alphanumeric traceability code
 Pb-free JEDEC designator for Matte Tin (Sn)

Note:

In the event of the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for the customer-specific information.

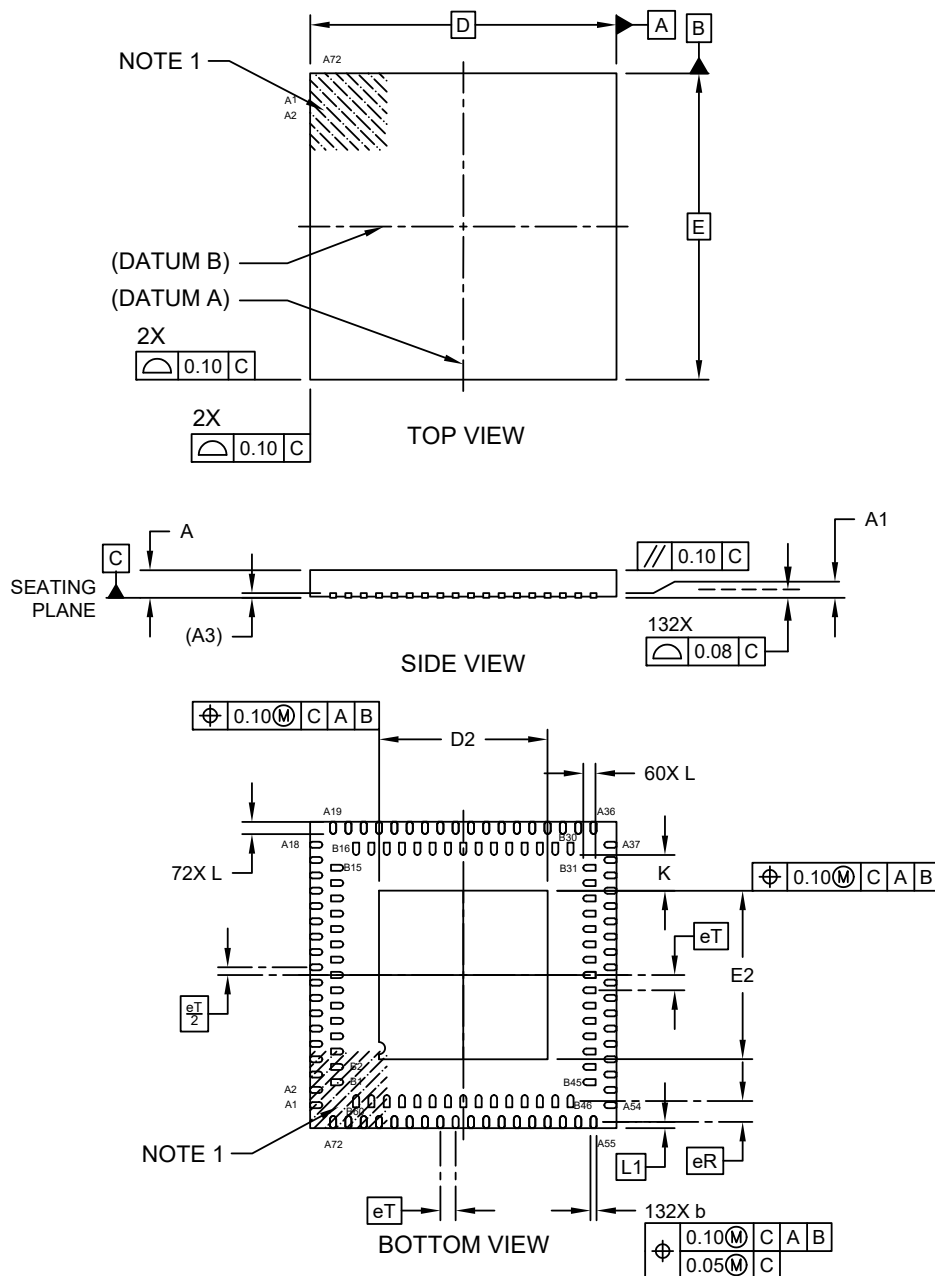
48.1.2. PIC32CX-BZ6 SoC Packaging Dimension

This section provides the package dimension details of the PIC32CX-BZ6 SoC.

48.1.2.1. PIC32CX2501BZ62132 SoC Packaging Dimension

**132-Lead Very Thin Plastic Quad Flat, No Lead Package (3WW) - 10x10x0.9 mm Body [VQFN]
Dual Row Terminals; Saw Singulated**

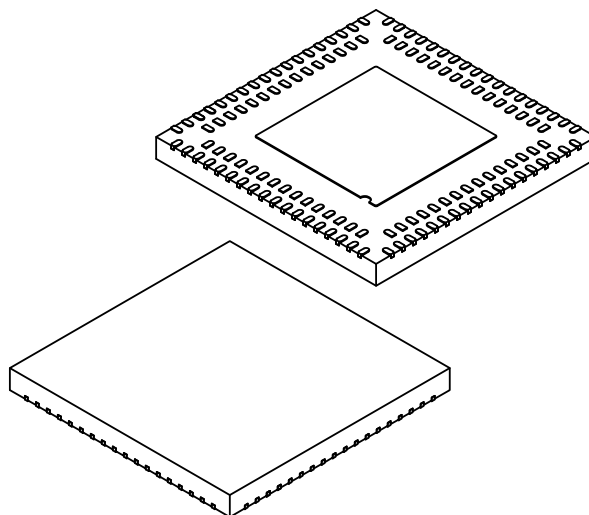
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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132-Lead Very Thin Plastic Quad Flat, No Lead Package (3WW) - 10x10x0.9 mm Body [VQFN] Dual Row Terminals; Saw Singulated

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Terminals	N	132		
Pitch	eT	0.50 BSC		
Outer Row Center to Inner Row Center	eR	0.65 BSC		
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.01	0.05
Terminal Thickness	A3	0.152 REF		
Overall Length	D	10.00 BSC		
Exposed Pad Length	D2	5.40	5.50	5.60
Overall Width	E	10.00 BSC		
Exposed Pad Width	E2	5.40	5.50	5.60
Terminal Width	b	0.17	0.22	0.27
Terminal Length	L	0.30	0.40	0.50
Inner Row Terminal Length	L2	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	—	—

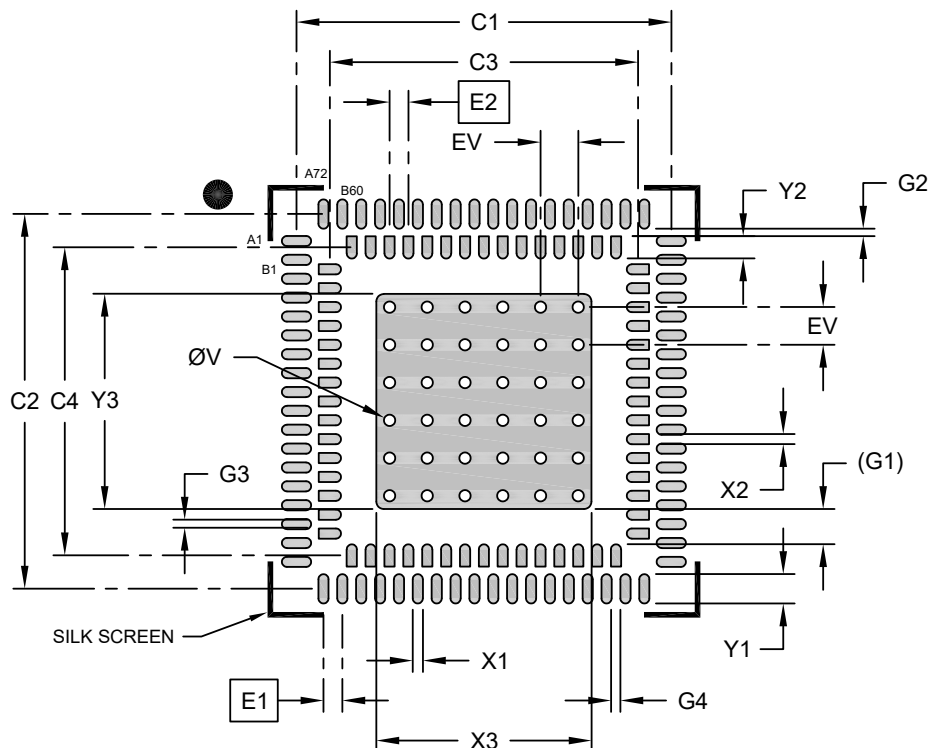
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

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132-Lead Very Thin Plastic Quad Flat, No Lead Package (3WW) - 10x10x0.9 mm Body [VQFN] Dual Row Terminals; Saw Singulated

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS			Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	Dimension Limits		MIN	NOM	MAX
Outer Contact Pitch	E1	0.50 BSC			Inner Contact Pad Spacing	C4		8.16	
Inner Contact Pitch	E2	0.50 BSC			Outer Contact Pad Length (X72)	Y1			0.78
Outer Contact Pad Width (X72)	X1			0.30	Inner Contact Pad Length (X60)	Y2			0.59
Inner Contact Pad Width (X60)	X2			0.30	Contact Pad to Center Pad (X60)	G1	1.20 REF		
Optional Center Pad Width	X3			5.60	Inner Pad Row to Outer Pad Row	G2	0.20		
Optional Center Pad Length	Y3			5.60	Contact Pad to Contact Pad (X68)	G3	0.20		
Outer Contact Pad Spacing	C1		9.93		Contact Pad to Contact Pad (X56)	G4	0.20		
Outer Contact Pad Spacing	C2		9.93		Thermal Via Diameter	V		0.30	
Inner Contact Pad Spacing	C3		8.16		Thermal Via Pitch	EV		1.00	

Notes:

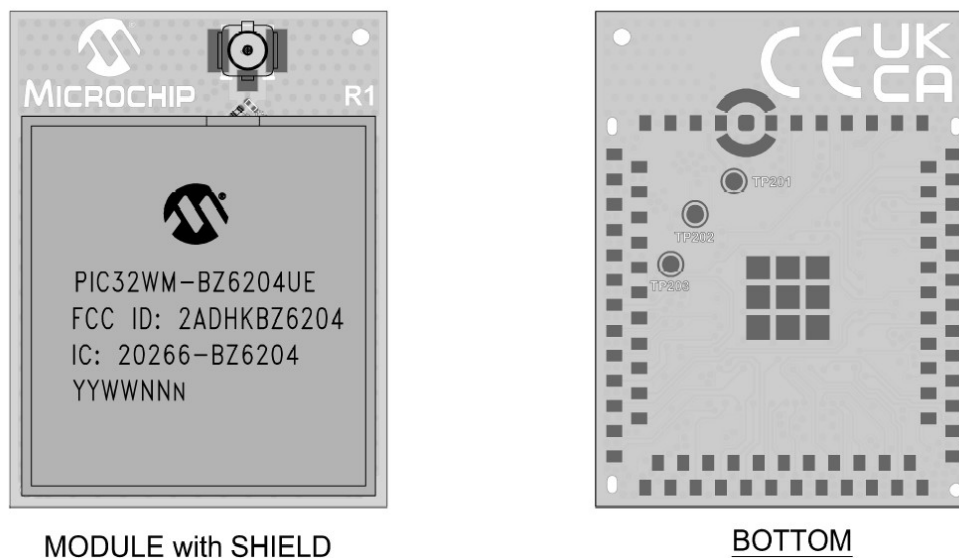
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2575 Rev. C

48.2. PIC32WM-BZ6 Module Packaging Information

48.2.1. PIC32WM-BZ6204 Packaging Marking

Figure 48-2. PIC32WM-BZ6204 Package Marking



Legend

YY: Year code (last 2 digits of calendar year)

WW: Week code (week of January 1 is week "01")

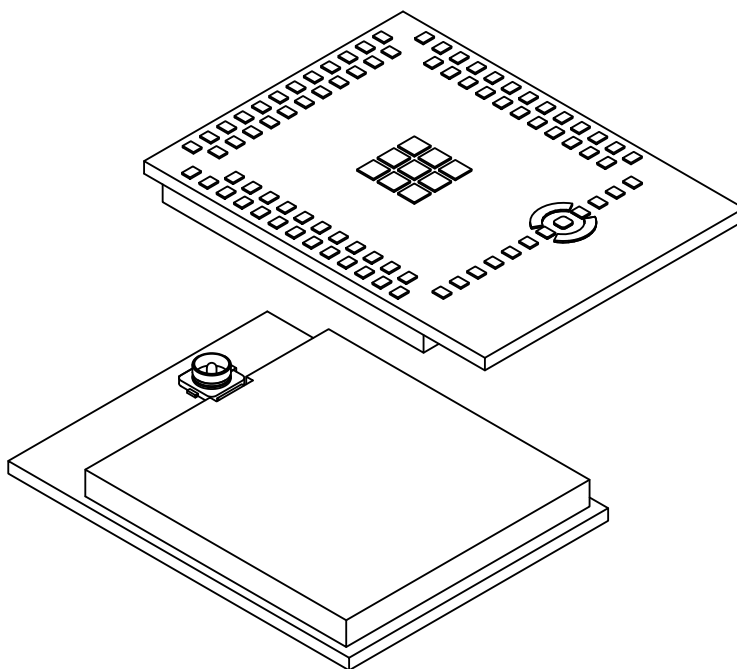
NNN: Alphanumeric traceability code

48.2.2. PIC32WM-BZ6 Module Packaging Dimension

This section provides the package dimension details of the PIC32WM-BZ6 Module.

82L-PCB Module (6TW) - 19x25x2.75 mm - [MODULE] with Metal Shield and Coaxial Connector

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	82		
Terminal Pitch	e	1.27 BSC		
Overall Height	A	2.60	2.75	2.90
PCB Thickness	A2	0.70	0.80	0.90
Shield Height	A3	1.80	1.85	1.90
Coaxial Connector Height	A4	1.25 REF		
Overall Length	D	18.90	19.00	19.10
Overall Width	E	24.90	25.00	25.05
Shield Length	D1	17.45	17.50	17.55
Shield Width	E1	18.74	18.79	18.84
Terminal Width	b	0.50	0.60	0.70
Terminal Length	L	0.70	0.80	0.90

Notes:

1. All Dimensions are in Millimeters

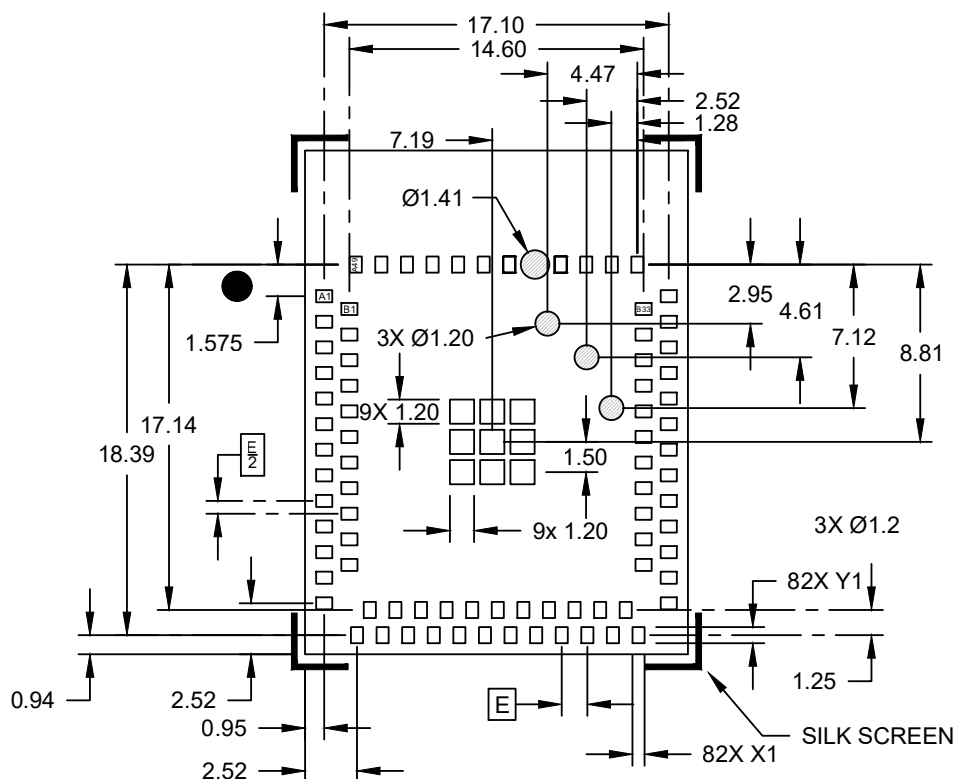
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

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82L-PCB Module (6TW) - 19x25x2.75mm - [MODULE] with Metal Shield and Coaxial Connector

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Width (Xnn)	X1			0.70
Contact Pad Length (Xnn)	Y1			1.00

● Copper Keep-Out Area for Test Point

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, please refer to IPC-7093.

Microchip Technology Drawing C04-02633 Rev D

49. Appendix A: Regulatory Approval

The PIC32WM-BZ6204UC Module has received regulatory approval for the following countries:

- United States/FCC ID: 2ADHKBZ6204
- Canada/ISED:
 - IC: 20266-BZ6204
 - HVIN: PIC32WM-BZ6204UC
 - PMN: Wireless MCU Module with Bluetooth® Low Energy 6.0 qualified, IEEE® 802.15.4
- Europe/CE

The PIC32WM-BZ6204UE Module has received regulatory approval for the following countries:

- United States/FCC ID: 2ADHKBZ6204
- Canada/ISED:
 - IC: 20266-BZ6204
 - HVIN: PIC32WM-BZ6204UE
 - PMN: Wireless MCU Module with Bluetooth® Low Energy 6.0 qualified, IEEE® 802.15.4
- Europe/CE

49.1. United States

The PIC32WM-BZ6204UE and PIC32WM-BZ6204UC Modules have received Federal Communications Commission (FCC) CFR47 Telecommunications, Part 15 Subpart C “Intentional Radiators” single-modular approval in accordance with Part 15.212 Modular Transmitter approval. Single-modular transmitter approval is defined as a complete RF transmission sub-assembly, designed to be incorporated into another device, that must demonstrate compliance with FCC rules and policies independent of any host. A transmitter with a modular grant can be installed in different end-use products (referred to as a host, host product or host device) by the grantee or other equipment manufacturer, then the host product may not require additional testing or equipment authorization for the transmitter function provided by that specific module or limited module device.

The user must comply with all of the instructions provided by the Grantee, which indicate installation and/or operating conditions necessary for compliance.

A host product itself is required to comply with all other applicable FCC equipment authorization regulations, requirements, and equipment functions that are not associated with the transmitter module portion. For example, compliance must be demonstrated: to regulations for other transmitter components within a host product; to requirements for unintentional radiators (Part 15 Subpart B), such as digital devices, computer peripherals, radio receivers, etc.; and to additional authorization requirements for the non-transmitter functions on the transmitter module (i.e., Suppliers Declaration of Conformity (SDoC) or certification) as appropriate (e.g., Bluetooth and Wi-Fi transmitter modules may also contain digital logic functions).

Changes or modifications not expressly approved by the party responsible for compliance could void the user’s authority to operate the equipment.

49.1.1. Labeling and User Information Requirements

The PIC32WM-BZ6204UE and PIC32WM-BZ6204UC Modules have been labeled with its own FCC ID number, and if the FCC ID is not visible when the module is installed inside another device, then the outside of the finished product into which the module is installed must display a label referring to the enclosed module. This exterior label must use the following wording:

Contains Transmitter Module FCC ID: 2ADHKBZ6204

or

Contains FCC ID: 2ADHKBZ6204

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

The user's manual for the finished product must include the following statement:

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy, and if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna
- Increase the separation between the equipment and receiver
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected
- Consult the dealer or an experienced radio/TV technician for help

Additional information on labeling and user information requirements for Part 15 devices can be found in KDB Publication 784748, which is available at the FCC Office of Engineering and Technology (OET) Laboratory Division Knowledge Database (KDB) apps.fcc.gov/oetcf/kdb/index.cfm.

49.1.2. RF Exposure

All transmitters regulated by FCC must comply with RF exposure requirements. KDB 447498 General RF Exposure Guidance provides guidance in determining whether proposed or existing transmitting facilities, operations or devices comply with limits for human exposure to Radio Frequency (RF) fields adopted by the Federal Communications Commission (FCC).

From the FCC Grant: Output power listed is conducted. This grant is valid only when the module is sold to OEM integrators and must be installed by the OEM or OEM integrators. This transmitter is restricted for use with the specific antenna(s) tested in this application for Certification and must not be co-located or operating in conjunction with any other antenna or transmitters within a host device, except in accordance with FCC multi-transmitter product procedures.

PIC32WM-BZ6204UE/PIC32WM-BZ6204UC: These modules are approved for installation into mobile host platforms at least 20 cm away from the human body.

49.1.3. Approved Antenna Types

To maintain modular approval in the United States, only the tested antenna types are used. It is permissible to use different antenna, provided the same antenna type, antenna gain (equal to or less than), with similar in-band and out-of band characteristics (refer to specification sheet for cutoff frequencies).

For the PIC32WM-BZ6204UE/PIC32WM-BZ6204UC, approved antennas are listed in the [Table 4-1](#).

49.1.4. Helpful Web Sites

- Federal Communications Commission (FCC): www.fcc.gov.
- FCC Office of Engineering and Technology (OET) Laboratory Division Knowledge Database (KDB) apps.fcc.gov/oetcf/kdb/index.cfm.

49.2. Canada

The PIC32WM-BZ6204UE and PIC32WM-BZ6204UC Modules have been certified for use in Canada under Innovation, Science and Economic Development Canada (ISED, formerly Industry Canada)

Radio Standards Procedure (RSP) RSP-100, Radio Standards Specification (RSS) RSS-Gen and RSS-247. Modular approval permits the installation of a module in a host device at least 20 cm distance.

49.2.1. Labeling and User Information Requirements

Labeling Requirements (from RSP-100 - Issue 12, Section 5): The host product shall be properly labeled to identify the module within the host device.

The Innovation, Science and Economic Development Canada certification label of a module shall be clearly visible at all times when installed in the host device; otherwise, the host product must be labeled to display the Innovation, Science and Economic Development Canada certification number of the module, preceded by the word “Contains” or similar wording expressing the same meaning, as follows:

For the PIC32WM-BZ6204UE and PIC32WM-BZ6204UC
Modules

Contains IC: **20266-BZ6204**

User Manual Notice for License-Exempt Radio Apparatus (from Section 8.4 RSS-Gen, Issue 5, February 2021): User manuals for license-exempt radio apparatus shall contain the following or equivalent notice in a conspicuous location in the user manual or alternatively on the device or both:

This device contains license-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada’s license-exempt RSS(s). Operation is subject to the following two conditions:

- (1) This device may not cause interference;**
- (2) This device must accept any interference, including interference that may cause undesired operation of the device.**

L’émetteur/récepteur exempt de licence contenu dans le présent appareil est conforme aux CNR d’Innovation, Sciences et Développement économique Canada applicables aux appareils radio exempts de licence. L’exploitation est autorisée aux deux conditions suivantes:

- 1. L’appareil ne doit pas produire de brouillage;**
- 2. L’appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d’en compromettre le fonctionnement.**

Transmitter Antenna (From Section 6.8 RSS-GEN, Issue 5, February 2021): User manuals, for transmitters shall display the following notice in a conspicuous location:

This radio transmitter 20266-BZ6204 has been approved by Innovation, Science and Economic Development Canada to operate with the antenna types listed below, with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.

Le présent émetteur radio 20266-BZ6204 a été approuvé par Innovation, Sciences et Développement économique Canada pour fonctionner avec les types d’antenne énumérés ci-dessous et ayant un gain admissible maximal. Les types d’antenne non inclus dans cette liste, et dont le gain est supérieur au gain maximal indiqué pour tout type figurant sur la liste, sont strictement interdits pour l’exploitation de l’émetteur.

Immediately following the above notice, the manufacturer shall provide a list of all antenna types approved for use with the transmitter, indicating the maximum permissible antenna gain (in dBi) and required impedance for each.

49.2.2. RF Exposure

All transmitters regulated by Innovation, Science and Economic Development Canada (ISED) must comply with RF exposure requirements listed in RSS-102 - Radio Frequency (RF) Exposure Compliance of Radiocommunication Apparatus (All Frequency Bands).

This transmitter is restricted for use with a specific antenna tested in this application for certification, and must not be co-located or operating in conjunction with any other antenna or transmitters within a host device, except in accordance with Canada multi-transmitter product procedures.

PIC32WM-BZ6204UE/PIC32WM-BZ6204UC: The device operates at an output power level which is within the ISED SAR test exemption limits at any user distance greater than 20 cm.

Exposition aux RF

Tous les émetteurs réglementés par Innovation, Sciences et Développement économique Canada (ISED) doivent se conformer à l'exposition aux RF, exigences énumérées dans RSS-102 - Conformité à l'exposition aux radiofréquences (RF) des appareils de radiocommunication (toutes les bandes de fréquences).

Cet émetteur est limité à une utilisation avec une antenne spécifique testée dans cette application pour la certification, et ne doit pas être colocalisé ou fonctionner conjointement avec une autre antenne ou émetteur au sein d'un appareil hôte, sauf conformément avec les procédures canadiennes relatives aux produits multi-transmetteurs.

Les appareils fonctionnent à un niveau de puissance de sortie qui se situe dans les limites du DAS ISED. tester les limites d'exemption à toute distance d'utilisateur supérieure à 20 cm.

49.2.3. Approved Antenna Types

For the PIC32WM-BZ6204UE/PIC32WM-BZ6204UC, approved antennas are listed in the [Table 4-1](#).

49.2.4. Helpful Web Sites

Innovation, Science and Economic Development Canada (ISED): www.ic.gc.ca/.

49.3. Europe

The PIC32WM-BZ6204UE/PIC32WM-BZ6204UC module is a Radio Equipment Directive (RED) assessed radio module that is CE marked and has been manufactured and tested with the intention of being integrated into a final product.

The PIC32WM-BZ6204UE and PIC32WM-BZ6204UC Modules have been tested to RED 2014/53/EU Essential Requirements mentioned in the following European Compliance table.

Table 49-1. European Compliance Information

Certification	Standard	Article
Safety	EN 62368	3.1a
Health	EN 62311, EN 62479	
EMC	EN 301 489-1	3.1b
	EN 301 489-17	
Radio	EN 300 328	3.2

The ETSI provides guidance on modular devices in the *"Guide to the application of harmonised standards covering articles 3.1b and 3.2 of the RED 2014/53/EU (RED) to multi-radio and combined radio and non-radio equipment"* document available at http://www.etsi.org/deliver/etsi_eg/203300_203399/20_3367/01.01.01_60/eg_203367v010101p.pdf.

Note: To maintain conformance to the standards listed in the preceding European Compliance table, the module shall be installed in accordance with the installation instructions in this data sheet and shall not be modified. When integrating a radio module into a completed product, the integrator becomes the manufacturer of the final product and is therefore responsible for demonstrating compliance of the final product with the essential requirements against the RED.

49.3.1. Labeling and User Information Requirements

The label on the final product that contains the PIC32WM-BZ6204UE/PIC32WM-BZ6204UC Module must follow CE marking requirements.

49.3.2. Conformity Assessment

From ETSI Guidance Note EG 203367, section 6.1, when non-radio products are combined with a radio product:

If the manufacturer of the combined equipment installs the radio product in a host non-radio product in equivalent assessment conditions (i.e. host equivalent to the one used for the assessment of the radio product) and according to the installation instructions for the radio product, then no additional assessment of the combined equipment against article 3.2 of the RED is required.

49.3.2.1. Simplified EU Declaration of Conformity

Hereby, Microchip Technology Inc. declares that the radio equipment type PIC32WM-BZ6204UE and PIC32WM-BZ6204UC Modules are in compliance with Directive 2014/53/EU.

The full text of the EU declaration of conformity, for this product, is available at its product webpage (under Documents > Certifications).

49.3.3. Approved Antenna Types

For the PIC32WM-BZ6204UE/PIC32WM-BZ6204UC, approved antennas are listed in the [Table 4-1](#).

49.3.4. Helpful Websites

A document that can be used as a starting point in understanding the use of Short Range Devices (SRD) in Europe is the European Radio Communications Committee (ERC) Recommendation 70-03 E, which can be downloaded from the European Communications Committee (ECC) at: docdb.cept.org/.

Additional helpful web sites are:

- Radio Equipment Directive (2014/53/EU):
https://ec.europa.eu/growth/single-market/european-standards/harmonised-standards/red_en
- European Conference of Postal and Telecommunications Administrations (CEPT):
<http://www.cept.org>
- European Telecommunications Standards Institute (ETSI):
<http://www.etsi.org>
- The Radio Equipment Directive Compliance Association (REDCA):
<http://www.redca.eu/>

49.4. UKCA (UK Conformity Assessed)

The PIC32WM-BZ6204UE/PIC32WM-BZ6204UC Module is a UK conformity assessed radio module that meets all the essential requirements according to CE RED requirements.

49.4.1. Labeling Requirements for Module and User's Requirements

The label on the final product that contains the PIC32WM-BZ6204UE/PIC32WM-BZ6204UC Module must follow UKCA marking requirements.



The UKCA mark above is printed on the module itself or on the packing label.

Additional details for the label requirement are available at:

<https://www.gov.uk/guidance/using-the-ukca-marking#check-whether-you-need-to-use-the-new-ukca-marking>.

49.4.2. UKCA Declaration of Conformity

Hereby, Microchip Technology Inc. declares that the radio equipment type the PIC32WM-BZ6204UE/ PIC32WM-BZ6204UC Modules are in compliance with the Radio Equipment Regulations 2017.

49.4.3. Approved Antennas

The testing of the PIC32WM-BZ6204UE/PIC32WM-BZ6204UC Module was performed with the antennas listed in [Table 4-1](#).

49.4.4. Helpful Websites

For more information on the UKCA regulatory approvals, refer to the www.gov.uk/guidance/placing-manufactured-goods-on-the-market-in-great-britain.

49.5. Other Regulatory Information

For information about other countries' jurisdictions not covered here, refer to the "Regulatory Approval Documentation Package" available on the respective module product pages. This package provides a complete list of countries and references to worldwide documentation.

50. Document Revision History

The document revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

Revision	Date	Section	Description
A	5/2025	Document	Initial revision

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